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FDC653N

N-Channel Enhancement Mode Field Effect Transistor

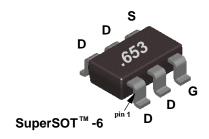
General Description

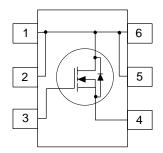
This N-Channel enhancement mode power field effect transistors is produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMICA cards, and other battery powered circuits where fast switching, and low in-line power loss are needed in a very small outline surface mount package.

Features

- Proprietary SuperSOTTM-6 package design using copper lead frame for superior thermal and electrical capabilities.
- High density cell design for extremely low R_{DS(ON)}.
- Exceptional on-resistance and maximum DC current capability.







Absolute Maximum Ratings $T_A = 25$ °C unless otherwise note

| Symbol | Parameter | | FDC653N | Units | | |
|----------------------------------|---|-----------|------------|-------|--|--|
| V _{DSS} | Drain-Source Voltage | | 30 | V | | |
| V _{GSS} | Gate-Source Voltage - Continuous | | ±20 | V | | |
| I _D | Drain Current - Continuous | (Note 1a) | 5 | Α | | |
| | - Pulsed | | 15 | | | |
| P _D | Maximum Power Dissipation | (Note 1a) | 1.6 | W | | |
| | | (Note 1b) | 0.8 | | | |
| T _J ,T _{STG} | Operating and Storage Temperature Range | | -55 to 150 | °C | | |
| THERMAL CHARACTERISTICS | | | | | | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 78 | °C/W | | |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | (Note 1) | 30 | °C/W | | |

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|----------------------------------|--|--|-----|-------|-------|--------|
| OFF CHAR | ACTERISTICS | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ | 30 | | | V |
| $\Delta BV_{DSS}/\Delta T_{J}$ | Breakdown Voltage Temp. Coefficient | $I_D = 250 \mu\text{A}$, Referenced to 25°C | | 31 | | mV /°C |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 24 \text{ V}, \ V_{GS} = 0 \text{ V}$ | | | 1 | μA |
| | | $T_{J} = 55^{\circ}C$ | | | 10 | μA |
| I _{GSSF} | Gate - Body Leakage, Forward | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| I _{GSSR} | Gate - Body Leakage, Reverse | V _{GS} = -20 V, V _{DS} = 0 V | | | -100 | nA |
| ON CHARA | CTERISTICS (Note 2) | | • | | • | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ | 1 | 1.7 | 2 | V |
| $\Delta V_{GS(th)}/\Delta T_{J}$ | Gate Threshold VoltageTemp.Coefficient | I _D = 250 μA, Referenced to 25 °C | | -4.2 | | mV /°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance | $V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$ | | 0.027 | 0.035 | Ω |
| . , | | T _J = 125°C | | 0.042 | 0.056 | 1 |
| | | $V_{GS} = 4.5 \text{ V}, I_{D} = 4.2 \text{ A}$ | | 0.046 | 0.055 | 1 |
| I _{D(on)} | On-State Drain Current | $V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$ | 8 | | | Α |
| g_{FS} | Forward Transconductance | $V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$ | | 6.2 | | S |
| DYNAMIC (| HARACTERISTICS | | | _ | | |
| C _{iss} | Input Capacitance | $V_{DS} = 15 \text{ V}, \ V_{GS} = 0 \text{ V},$ | | 350 | | pF |
| C _{oss} | Output Capacitance | f = 1.0 MHz | | 220 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 80 | | pF |
| SWITCHING | CHARACTERISTICS (Note 2) | | | | | |
| t _{D(on)} | Turn - On Delay Time | $V_{DD} = 10 \text{ V}, I_{D} = 1 \text{ A},$ | | 7.5 | 15 | ns |
| t _r | Turn - On Rise Time | $V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$ | | 12 | 25 | ns |
| t _{D(off)} | Turn - Off Delay Time | | | 13 | 25 | ns |
| t, | Turn - Off Fall Time | | | 6 | 15 | ns |
| Q_g | Total Gate Charge | $V_{DS} = 15 \text{ V}, I_{D} = 5 \text{ A},$ | | 12 | 17 | nC |
| Q_{gs} | Gate-Source Charge | V _{GS} = 10 V | | 2.1 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 2.6 | | nC |
| DRAIN-SOL | RCE DIODE CHARACTERISTICS | | | | | |
| l _s | Continuous Source Diode Current | | | | 1.3 | Α |
| V _{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_{S} = 1.3 \text{ A}$ (Note 2) | | 0.75 | 1.2 | V |
| | | T = 125°C | | 0.6 | 1 | |

Notes

^{1.} R_{Bulk} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{Buc} is guaranteed by design while R_{Bck} is determined by the user's board design.

a. 78°C/W when mounted on a minimum on a 1 in² pad of 2oz Cu in FR-4 board.

b. 156°C/W when mounted on a minimum pad of 2oz Cu in FR-4 board.

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

Typical Electrical Characteristics

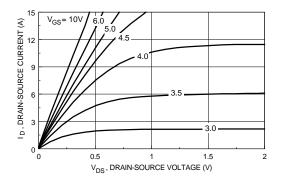
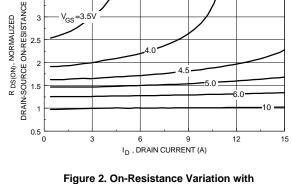


Figure 1. On-Region Characteristics.



3.5

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

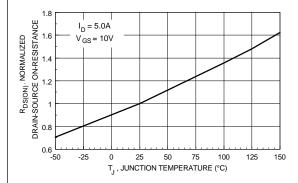


Figure 3. On-Resistance Variation with Temperature.

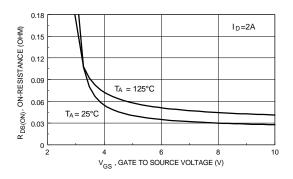


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

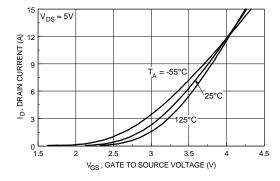


Figure 5. Transfer Characteristics.

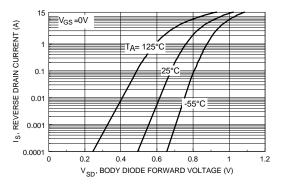


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical And Thermal Characteristics

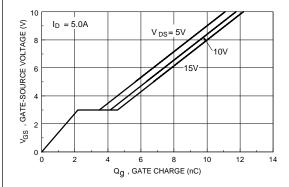


Figure 7. Gate Charge Characteristics.

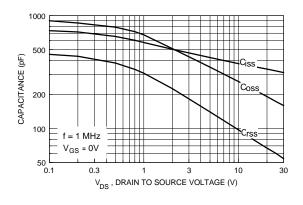


Figure 8. Capacitance Characteristics.

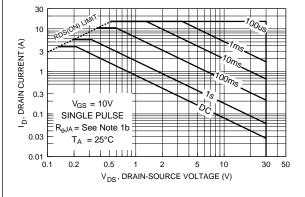


Figure 9. Maximum Safe Operating Area.

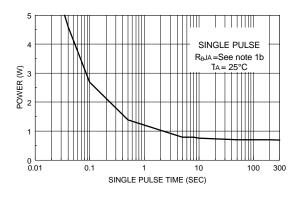


Figure 10. Single Pulse Maximum Power Dissipation.

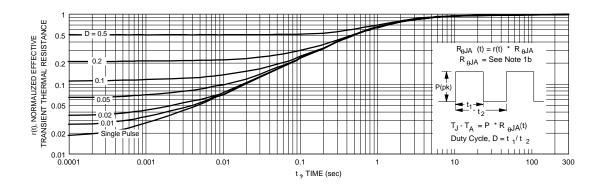


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1b.Transient thermal response will change depending on the circuit board design.

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